2SC4152

Silicon NPN triple diffusion planar type

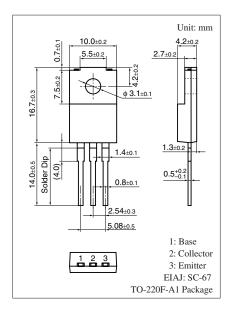
For high breakdown voltage high-speed switching

■ Features

- High-speed switching
- High collector-base voltage (Emitter open) V_{CBO}
- Wide safe operation area
- Satisfactory linearity of forward current transfer ratio h_{FE}
- Full-pack package which can be installed to the heat sink with one screw

■ Absolute Maximum Ratings $T_C = 25$ °C

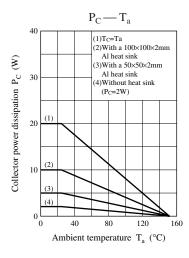
Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	V _{CBO}	1 400	V
Collector-emitter voltage (Resistor between B and E)	V _{CER}	1 400	V
Collector-emitter voltage (Base open)	V _{CEO}	700	V
Emitter-base voltage (Collector open)	V_{EBO}	5	V
Collector current	I_C	0.3	A
Peak collector current	I_{CP}	1.0	A
Collector power dissipation	P _C	20	W
$T_a = 25^{\circ}C$		2.0	
Junction temperature	T_{j}	150	°C
Storage temperature	T _{stg}	-55 to +150	°C

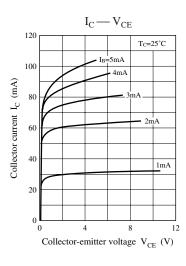


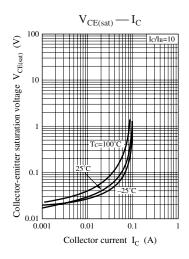
■ Electrical Characteristics $T_C = 25$ °C ± 3 °C

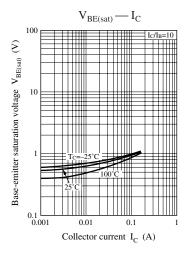
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-emitter voltage	V _{CER}	$I_C = 1 \text{ mA}, R_{BE} = 100 \Omega$	1 400			V
(Resistor between B and E)						
Collector-emitter voltage (Base open)	V _{CEO}	$I_C = 1 \text{ mA}, I_B = 0$	700			V
Emitter-base voltage (Collector open)	V_{EBO}	$I_E = 1 \text{ mA}, I_C = 0$	5			V
Collector-base cutoff current (Emitter open)	I_{CBO}	$V_{CB} = 1 100 V, I_E = 0$			10	μΑ
Emitter-base cutoff current (Collector open)	I_{EBO}	$V_{EB} = 4 \text{ V}, I_{C} = 0$			10	μΑ
Forward current transfer ratio	h_{FE}	$V_{CE} = 5 \text{ V}, I_{C} = 30 \text{ mA}$	10		40	_
Collector-emitter saturation voltage	V _{CE(sat)}	$I_C = 60 \text{ mA}, I_B = 6 \text{ mA}$			2	V
Base-emitter saturation voltage	V _{BE(sat)}	$I_C = 60 \text{ mA}, I_B = 6 \text{ mA}$			2	V
Transition frequency	f_T	$V_{CE} = 10 \text{ V}, I_{C} = 30 \text{ mA}, f = 1 \text{ MHz}$		12		MHz
Collector output capacitance	C _{ob}	$V_{CB} = 100 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		6		pF
(Common base, input open circuited)						
Turn-on time	t _{on}	$I_C = 0.15$ A, Resistance loaded			2	μs
Storage time	t _{stg}	$I_{B1} = 15 \text{ mA}, I_{B2} = -30 \text{ mA}$			3	μs
Fall time	$t_{\rm f}$	$V_{CC} = 250 \text{ V}$			1	μs

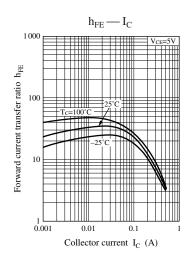
Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

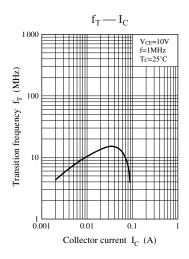


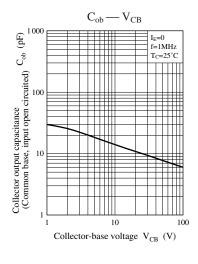


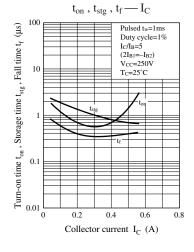


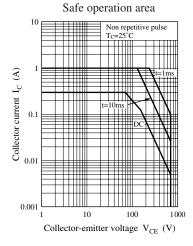




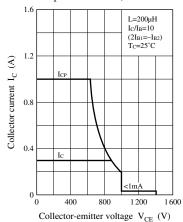




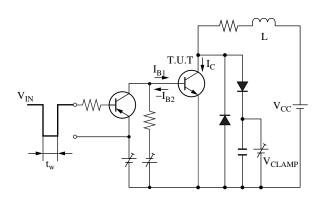


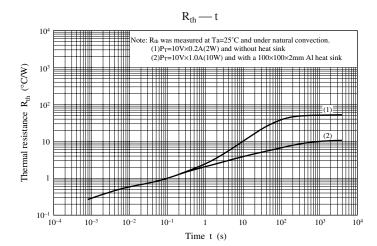


Safe operation area (Reverse bias)



Safe operation area (Reverse bias) measurement circuit





SJD00126BED 3

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